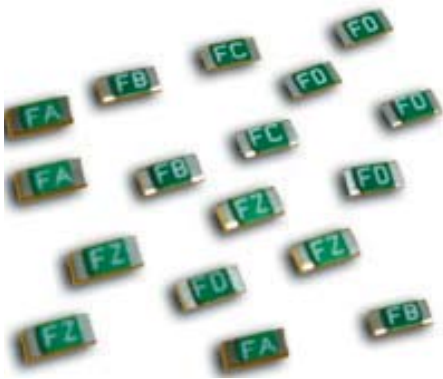




SMD1206 Series

Surface Mount PTC



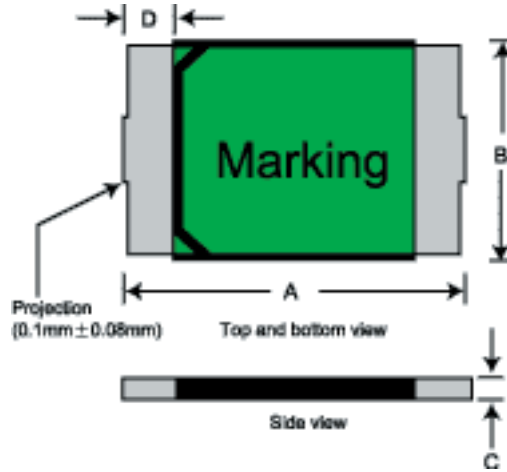
Application:	All high-density boards
Product Features:	Small surface mount, Solid state Faster time to trip than standard SMD devices Lower resistance than standard SMD devices
Operation Current:	50mA~1.5A
Maximum Voltage:	6V~60V
Temperature Range:	-40°C to 85°C
Agency Recognition:	UL & C-UL

Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Maximum Current	Typical Power	Max Time to Trip		Resistance Tolerance	
						Current	Time	RMIN	R1MAX
								ohms	ohms
SMD1206-005-60	0.05	0.15	60	10	0.4	0.25	1.50	3.600	50.00
SMD1206-010-60	0.10	0.25	60	10	0.4	0.50	1.00	2.100	15.00
SMD1206-020-30	0.20	0.40	30	10	0.4	8.00	0.05	0.600	2.50
SMD1206-035-16	0.35	0.75	16	40	0.4	8.00	0.10	0.300	1.20
SMD1206-050-8	0.50	1.00	8	40	0.4	8.00	0.10	0.150	0.70
SMD1206-075-6	0.75	1.50	6	40	0.6	8.00	0.20	0.100	0.29
SMD1206-100-6	1.00	1.80	6	40	0.6	8.00	0.30	0.055	0.21
SMD1206-150-6	1.50	3.00	6	40	0.8	8.00	1.00	0.040	0.12

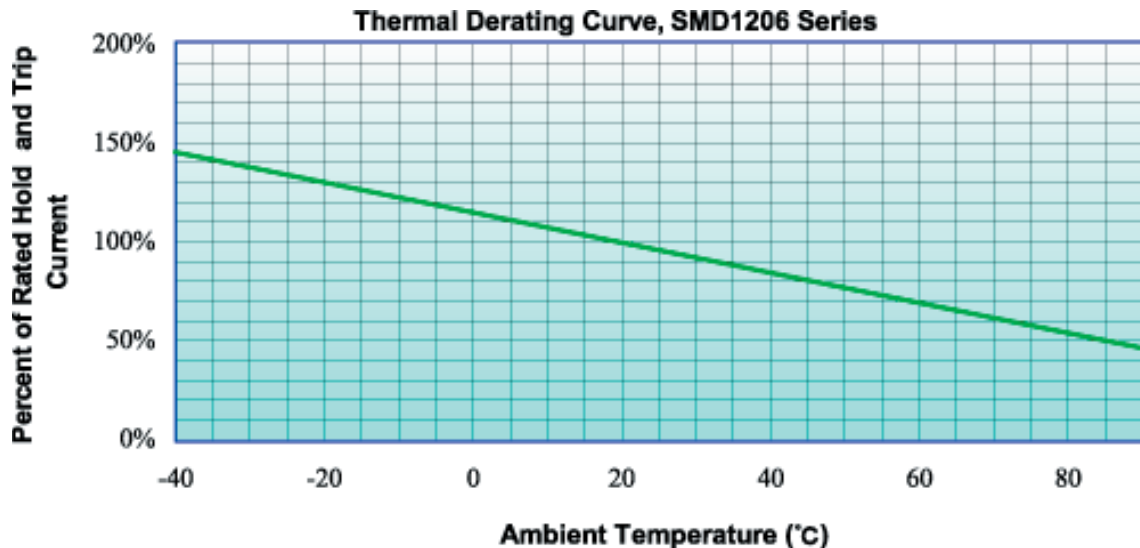
IH=Hold current-maximum current at which the device will not trip at 23°C still air.
 IT=Trip current-minimum current at which the device will always trip at 23°C still air.
 V MAX=Maximum voltage device can withstand without damage at its rated current.
 I MAX= Maximum fault current device can withstand without damage at rated voltage (V max).
 Pd=Typical power dissipated from device when in the tripped state in 23°C still air environment.
 RMIN=Minimum device resistance at 23°C.
 R1MAX=Maximum device resistance at 23°C, 1 hour after tripping .
 Termination pad characteristics
 Termination pad materials: solder-plated copper

SMD1206 Product Dimensions (Millimeters)



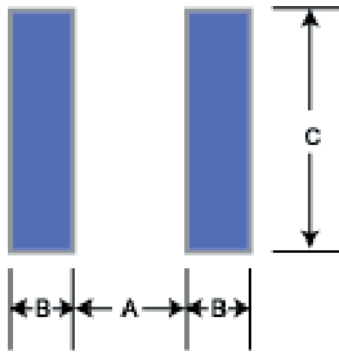
Part Number	A		B		C		D
	Min	Max	Min	Max	Min	Max	Min
SMD1206-005-60	3.0	3.5	1.5	1.8	0.45	0.75	0.10
SMD1206-010-60	3.0	3.5	1.5	1.8	0.45	0.75	0.10
SMD1206-020-30	3.0	3.5	1.5	1.8	0.45	0.75	0.10
SMD1206-035-16	3.0	3.5	1.5	1.8	0.45	0.75	0.10
SMD1206-050-8	3.0	3.5	1.5	1.8	0.25	0.55	0.10
SMD1206-075-6	3.0	3.5	1.5	1.8	0.45	1.25	0.10
SMD1206-100-6	3.0	3.5	1.5	1.8	0.45	1.25	0.10
SMD1206-150-6	3.0	3.5	1.5	1.8	0.80	1.80	0.10

Thermal Derating Curve



Pad Layouts, Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each SMD1206 device



Pad dimensions (millimeters)			
Device	A	B	C
	Nominal	Nominal	Nominal
SMD1206-005-60	2.00	1.00	1.90
SMD1206-010-60	2.00	1.00	1.90
SMD1206-020-30	2.00	1.00	1.90
SMD1206-035-20	2.00	1.00	1.90
SMD1206-050-16	2.00	1.00	1.90
SMD1206-075-8	2.00	1.00	1.90
SMD1206-110-6	2.00	1.00	1.90
SMD1206-150-6	2.00	1.00	1.90

Solder reflow

Due to "Lead Free" nature, up to 40 seconds Dwelling time for the soldering zone is strongly recommend .

1. Recommended reflow methods; IR, vapor phase oven, hot air oven.
2. The SMD1206 Series are suitable for use with wave-solder application methods.
3. Recommended maximum paste thickness is 0.25mm.
4. Devices can be cleaned using standard industry methods and solvents.

CAUTION:

If reflow temperatures exceed the recommended Profile, devices may not meet the performance requirements.

Rework:

Use standard industry practices.

